COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
<thead>
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<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: PMP9668</th>
<th>REV: A</th>
<th>SUN REV: Not In VersionControl</th>
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<tbody>
<tr>
<td></td>
<td>IGNORE -&gt;</td>
<td></td>
<td>Bottom Overlay</td>
</tr>
</tbody>
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| PLOT NAME = Bottom Assembly Drawing | GENERATED : 4/15/2014 7:32:47 AM | TEXAS INSTRUMENTS |
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